

MA6X127 (MA127)

Silicon epitaxial planar type

For switching circuit

■ Features

- Four isolated elements contained in one package, allowing high-density mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- The mirror image wiring of MA6X122 (MA122)
- High breakdown voltage: $V_R = 80$ V

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current *1	I_F	100	mA
Peak forward current *1	I_{FM}	225	mA
Non-repetitive peak forward surge current *1,2	I_{FSM}	500	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *1: Value for single diode

*2: $t = 1$ s

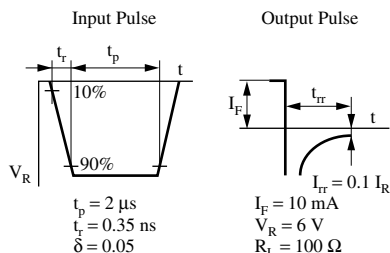
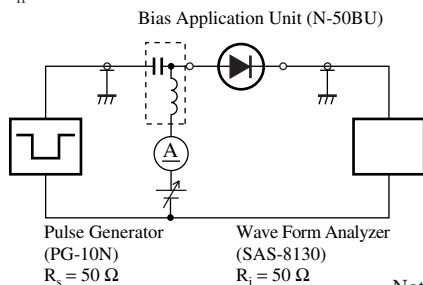
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.2	V
Reverse voltage	V_R	$I_R = 100$ μA	80			V
Reverse current	I_R	$V_R = 75$ V			100	nA
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz			15	pF
Reverse recovery time *	t_{rr}	$I_F = 10$ mA, $V_R = 6$ V $I_{rr} = 0.1 I_R$, $R_L = 100$ Ω			10	ns

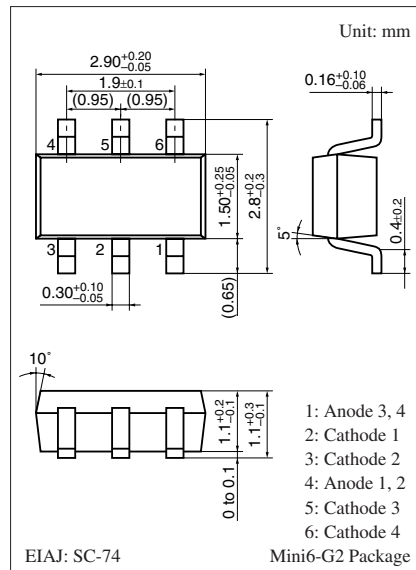
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *: t_{rr} measurement circuit

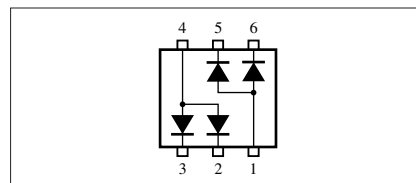


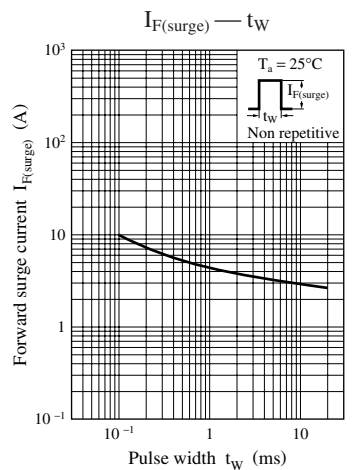
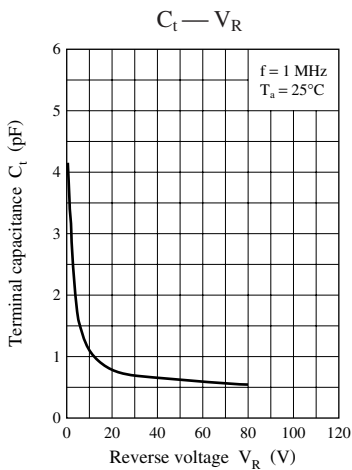
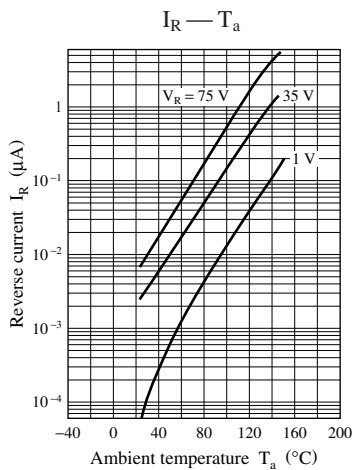
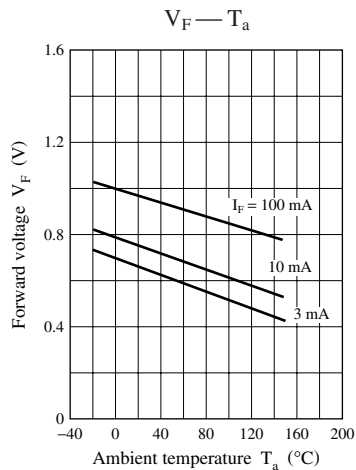
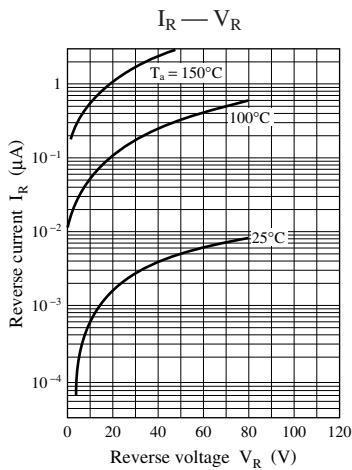
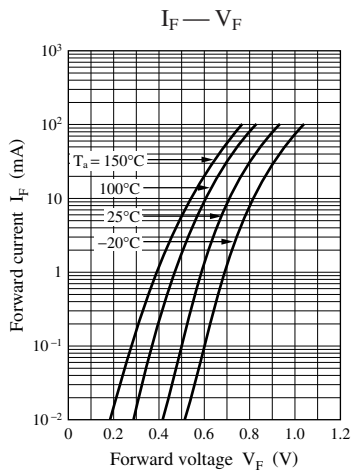
Note) The part number in the parenthesis shows conventional part number.



Marking Symbol: M2U

Internal Connection





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